**Attachement 1**

**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

1. GaAs N-type 3” SSP 100 pieces

1. **The scope of the subject of the contract**

A detailed description of the subject of the contract is provided in section 5 of this document.

1. **Criterion**

Offers will be evaluated according to a point scale with a maximum number of points of 100.

|  |  |  |
| --- | --- | --- |
| Criterion | Maximum number of points S | Method of awarding points |
| Net price (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of goods with delivery - for the given offer
* Pmin - the minimum delivery net price for the ordered goods from all offers submitted
* S – number of points

The final score will be calculated by adding up the partial components and then rounded to two decimal places. (rounded from "5" up)

1. **Deadline for completing the order**

Up to 9 weeks from the date of placing the order. The Ordering Party requires the application of the EXW Incoterms 2020 delivery principle. EXW (ex works), i.e. the moment of delivery of the goods is considered to be at the disposal of the buyer in the area indicated by the supplier (factory, plant, etc.).

1. **Parameters**

|  |  |  |
| --- | --- | --- |
| Product name | Parametrer | Specification |
| **GaAs N-type**  | Diameter 3” Thickness: 625±25 µm Diameter: 76.2±0.1 mm | Grade: | Prime, Epi-ready |
| Dopant | Si |
| Orientation: | (100)±0.1o |
| Primary Flat: | EJ (0-1-1) ±1o |
| Secondary Flat | EJ (0-11) ±2o |
| Carrier Conc.: | 0.8-4 E18/cm3 |
| EPD (Average): | 500/cm2 max |
| TTV: | 15 micr. max |
| TIR: | 10 micr. max |
| Warp: | 15 micr. max |
| Off-orientation | No miscut |
| Surface Finish: | SSP (single side polished)  |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |